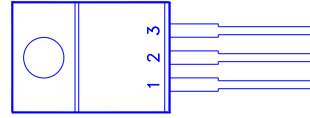
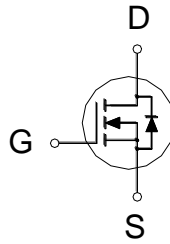




PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
110V	16m Ω	51A



1.GATE
2.DRAIN
3.SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ²	I_D	$T_C = 25\text{ }^\circ\text{C}$	51
		$T_C = 100\text{ }^\circ\text{C}$	32
Pulsed Drain Current ^{1,2}	I_{DM}	150	A
Avalanche Current	I_{AS}	12	
Avalanche Energy	E_{AS}	72	mJ
Power Dissipation	P_D	$T_C = 25\text{ }^\circ\text{C}$	96
		$T_C = 100\text{ }^\circ\text{C}$	38
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.3	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	$^\circ\text{C} / \text{W}$

¹Pulse width limited by maximum junction temperature.

²Limited only by maximum temperature allowed.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

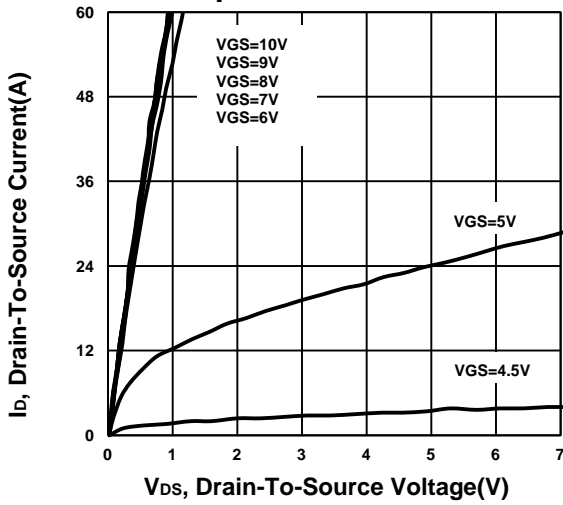
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	110			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3.2	4	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 88V, V_{GS} = 0V$			1	μA
		$V_{DS} = 80V, V_{GS} = 0V, T_J = 125\text{ }^\circ\text{C}$			10	

Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 7V, I _D = 15A	14	21	mΩ
		V _{GS} = 10V, I _D = 20A	13	16	
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 20A	80		S
DYNAMIC					
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	3009		pF
Output Capacitance	C _{oss}		258		
Reverse Transfer Capacitance	C _{rss}		152		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	0.81		Ω
Total Gate Charge ²	Q _g	V _{DS} = 55V, V _{GS} = 10V, I _D = 20A	57		nC
Gate-Source Charge ²	Q _{gs}		15.8		
Gate-Drain Charge ²	Q _{gd}		20		
Turn-On Delay Time ²	t _{d(on)}	V _{DD} = 55V I _D ≅ 20A, V _{GS} = 10V, R _{GEN} = 6Ω	47		nS
Rise Time ²	t _r		88		
Turn-Off Delay Time ²	t _{d(off)}		86		
Fall Time ²	t _f		83		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)					
Continuous Current	I _S			51	A
Forward Voltage ¹	V _{SD}	I _F = 20A, V _{GS} = 0V		1.2	V
Reverse Recovery Time	t _{rr}	I _F = 20A, dI _F /dt = 100A / μS	37		nS
Reverse Recovery Charge	Q _{rr}		50		nC

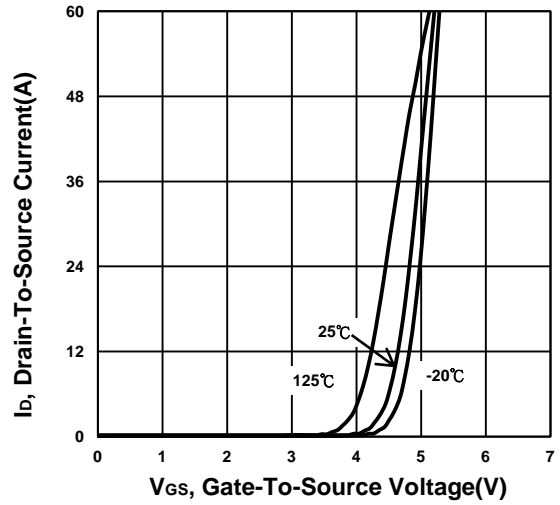
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

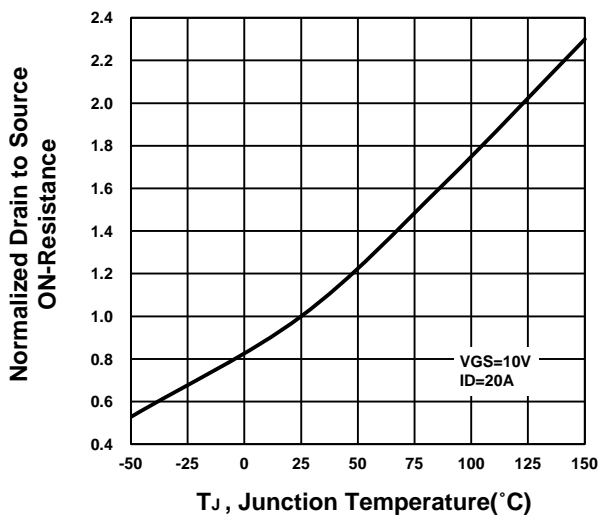
Output Characteristics



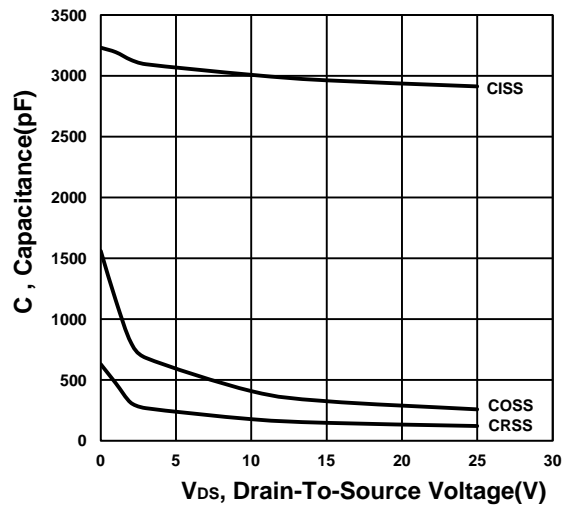
Transfer Characteristics



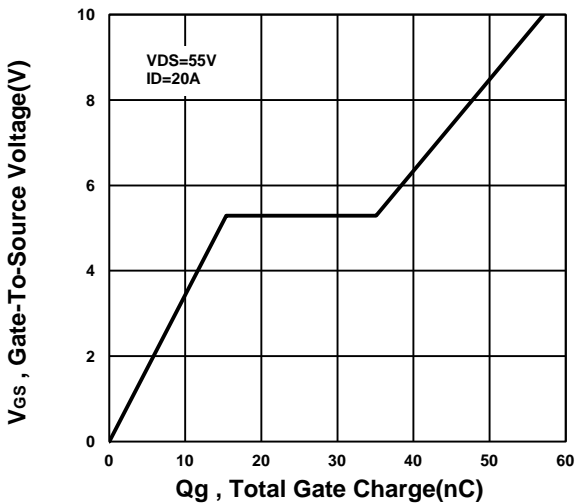
On-Resistance VS Temperature



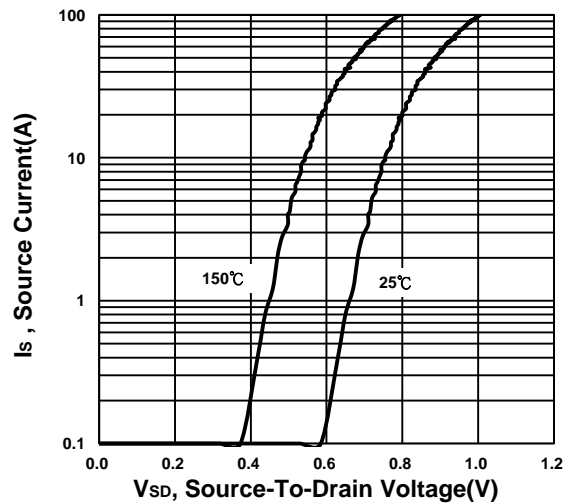
Capacitance Characteristic



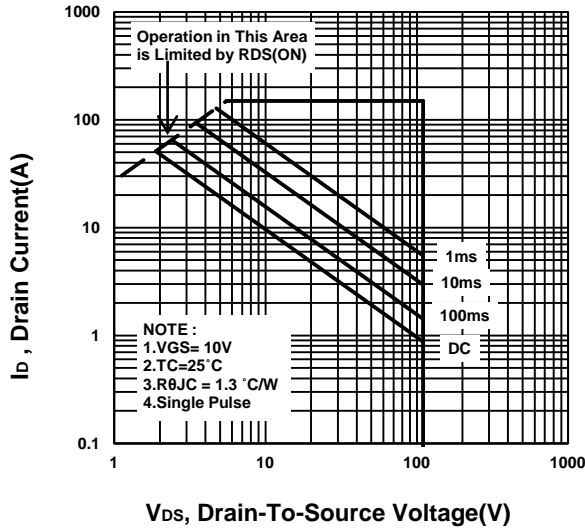
Gate charge Characteristics



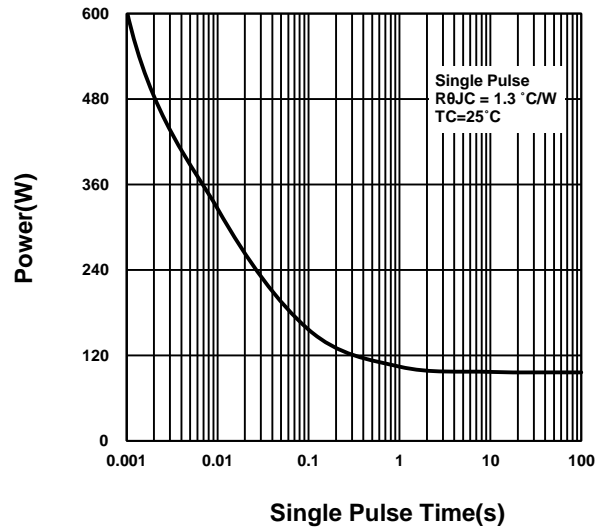
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

